Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	3034	(chip or circuit) same substrate same bump same (transparent or visible or protect\$4)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 16:48
S2	493	(chip or circuit) same substrate same bump same (transparent or visible or protect\$4) same underfill	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 16:48
S3	515	(chip or circuit) same substrate same bump same (transparent or visible or protect\$4) same underfill\$4	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 16:52
54	178	(chip or circuit) same substrate same bump same (transparent or visible or protect\$4) same underfill\$4 same ball	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 17:12
S5	26	"flip chip" same (barcode or "bar code")	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 16:49
S6	0	(chip or circuit) same substrate same bump same (transparent or visible or protect\$4) same underfill\$4 same (indicia or barcode or code or "machine readable" or label or tag or id or identifier or identification)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 16:53
S7	178	(chip or circuit) same substrate same bump same ball same (transparent or visible or protect\$4) same underfill\$4	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 16:53
S8	7	438/108.ccls. and (barcode or "bar code")	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 17:04
S9	26	("flip chip" or "flip-chip") same (barcode or "bar code")	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 17:05
S10	26	S9 not S8	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 17:05
S11	0	(chip or circuit or semiconductor or module or package) same substrate same bump same (transparent or visible or protect\$4) same underfill\$4 same ball and (barcode or "bar code")	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 17:12
S12	2	(chip or circuit or semiconductor or module or package) and substrate same bump same underfill\$4 same ball and (barcode or "bar code")	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 17:16
S13	2	(chip or circuit or semiconductor or module or package or ic) and substrate same bump same underfill\$4 same ball and (barcode or "bar code")	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 17:22

S14	2	(chip or circuit or semiconductor or module or package or ic) and substrate same (solder or bump) same underfill\$4 same (bga or ball) and (barcode or "bar code")	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 17:24
S15	468	("flip chip" or "flip-chip" or bga) and (barcode or "bar code")	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 17:24
S16	10	("flip chip" or "flip-chip") and (bump or solder\$3 or via) and underfill\$4 and (ball or bga) and (barcode or "bar code")	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 17:28
S17	275	"235"/\$.ccls. and (barcode or "bar code" or indicia or "machine readable" or code or id or identifier or identification) and (chip or die or semiconductor or package or module or "flip-chip" or circuit or ic) and (bga or ball) and (bump or solder or trace or via) and substrate	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 17:45
S18	102	257/678-797.ccls. and ("flip-chip" or "flip chip" or chip or ic or module or package or semiconductor or die) same (substrate or base) same underfill\$4 same (solder or pad or trace or via or bump) same (bga or ball) and (barcode or "bar code" or indicia or "machine readable" or id or identifier)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 17:49
S19	46	257/678-797.ccls. and ("flip-chip" or "flip chip" or chip or ic or module or package or semiconductor or die) same (substrate or base) same underfill\$4 same (solder or pad or trace or via or bump) same (bga or ball) and (barcode or "bar code" or indicia or "machine readable" or identifier or identification)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 17:57
S20	0	253/678,680,730,778,787.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 18:00
S21	0	253/678,680,730,778,787.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 18:00
S22	10943	257/678,680,730,778,787.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 18:00
S23	60	S22 and (barcode or "bar code")	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 18:04

S24	2	("4787143" "5197650").pn.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 18:05
S25	799	("257"/\$.ccls. "438"/\$.ccls. "235"/\$. ccls.) and (barcode or "bar code" or "machine readable" or indicia or identification or id or identifier) and (package or chip or semiconductor or ic or circuit or "flip-chip") and (lead or via or trace or solder or pad or bump) and (ball or bga) and underfill\$4	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 18:39
S26	239	("257"/\$.ccls. "438"/\$.ccls. "235"/\$.ccls.) and (barcode or "bar code" or "machine readable" or indicia or identification or id or identifier or label) and (package or chip or semiconductor or ic or circuit or "flip-chip") and (lead or via or trace or solder or pad or bump) and (ball or bga) and underfill\$4 and (transparent or clear or transmiss\$4 or "non opaque" or "non-opaque")	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 18:50
S27	15	S26 and (barcode or "bar code")	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 19:09
S28	1	"5984190".pn.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 19:09
S29	3	("5984190" "5539976" "5539976" "6478223").pn.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 19:10
S30	3	("5984190" "5539976" "6478223").pn.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 23:01
S31	70	"257"/\$.ccls. and (semiconductor or chip or ic or "integrated circuit" or module or package) same (barcode or "bar code" or symbol\$4 or indicia or code or "machine readable") and (bump or trace or via or solder) and (ball or bga) and substrate and underfill\$4	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 23:05

S32		"257"/\$.ccls. and (semiconductor or chip or ic or "integrated circuit" or module or package) same (barcode or "bar code" or symbol\$4 or indicia or code or "machine readable") and (bump or trace or via or solder) and (ball or bga or pbga) and substrate and underfill\$4 and (clear or transparent or translucent or "non opaque" or "non-opaque" or visible or readable)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 23:15
S33	11	("5970321" "5973395" "5461545" "5641997" "4300184" "5479049" "5834340" "5866949" "5925934" "5951804" "5955784").pn.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/21 23:16
S34	0	S33 and (barcode or "bar code" or symbol\$4 or "machine readable" or indicia or code)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/22 06:29
S35		("257"/\$.ccls.) and (semiconductor or chip or ic or circuit or package or module) same substrate same (encapsula\$4 or protect\$4 or seal\$4) same (clear or transparent or transmissive or "non opaque" or "non-opaque") same (barcode or "bar code" or symbol\$4 or indicia or marking or mark) same substrate and (ball or pbga or bga or trace or via or pads or "flip chip" or "flip-chip")	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/22 06:40
S36	1037	("257"/\$.ccls. "438"/\$.ccls.) and (barcode or "bar code")	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/22 07:21
S37	163	("257"/\$.ccls. "438"/\$.ccls.) and (barcode or "bar code") same (transparent or clear or transmissive or "non opaque" or "non-opaque" or encapsula\$4 or protect\$4 or glu\$4 or adhesiv\$4 or visible)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/22 07:52
S38	18	("5644102" "5346738" "5279690" "5118369" "5013900" "6337122" "6200828" "20020036235" "4719502" "5801067" "4312026" "6746053" "6476499" "5129974" "5984190" "5539976" "6478223").pn.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/22 08:08
S39	4099	("174"/\$.ccls. "156"/\$.ccls. "29"/\$.ccls.) and (code or barcode or "bar code" or indicia or code or "machine readable" or symbol\$4) same (chip or circuit or ic or semiconductor or module or package or device)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/22 08:09

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S40	328	("174"/\$.ccls. "156"/\$.ccls. "29"/\$.ccls.) and (code or barcode or "bar code" or indicia or code or "machine readable" or symbol\$4) same (chip or circuit or ic or semiconductor or module or package or device) same (transparent or clear or transmissive or "non opaque" or "non-opaque" or visible)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/22 08:10
S41	550	("174"/\$.ccls. "156"/\$.ccls. "29"/\$.ccls.) and (code or barcode or "bar code" or indicia or code or "machine readable" or symbol\$4) same (chip or circuit or ic or semiconductor or module or package or device) same (transparent or clear or transmissive or "non opaque" or "non-opaque" or visible or encapsul\$4 or protect\$4)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/22 08:11
S42	139	("flip-chip" or "flip chip") and ("transparent cover")	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 02:22
S43	43	("flip-chip" or "flip chip") same ("transparent cover")	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 02:29
S44	1	"5641997".pn.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 02:31
S45	1	"5461545".pn.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 02:32
S46	1489406	"flip chip" same encapsulat\$4 (transparent or clear)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 02:33
S47	118	"flip chip" same encapsula\$4 same (transparent or clear)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 02:33
S48	1497	CSP same "flip chip"	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 02:42
S49	3	CSP same "flip chip" same cap	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 02:43
S50	26	(CSP or "flip chip") same cap with (clear or transparent)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 02:46
S51	9	"flip chip" same (glass) near3 (window or cap or cover) and underfill	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 02:47

S52	10503	die same (barcode or "bar code" or mark or marking or symbol\$3)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 02:52
S53	5859	die with (barcode or "bar code" or mark or marking or symbol\$3)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 02:52
S54	0	die with (barcode or "bar code" or mark or marking or symbol\$3) same (cover or cap) with (transparent or clear) and (CSP or flip)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 02:52
S55	3	die with (barcode or "bar code" or mark or marking or symbol\$3) same (cover or cap) with (transparent or clear)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 02:53
S56	56	("257"/\$.ccls. "428"/\$.ccls.) and (die with (barcode or "bar code" or mark or marking or symbol\$3) same (flip))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 02:55
S57	7	("257"/\$.ccls. "428"/\$.ccls.) and (die with (barcode or "bar code" or mark or marking or symbol\$3) same (flip)) same (transparent or clear)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 03:00
S58	134	("257"/\$.ccls. "428"/\$.ccls.) and "flip chip" and "transparent epoxy"	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 03:01
S59	172	("257"/\$.ccls. "428"/\$.ccls.) and "flip chip" and "transparent resin"	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 03:00
S60	61	("257"/\$.ccls. "428"/\$.ccls.) and "flip chip" and "transparent epoxy" same (cover or cap or top)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 03:01
S61	10	("257"/\$.ccls. "428"/\$.ccls.) and "flip chip" and "transparent epoxy" with (cover or cap or top)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 03:03
S62	209	("257"/\$.ccls. "428"/\$.ccls.) and "flip chip" same (transparent or clear) same (cover or cap or top) and chip	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 03:04
S63	209	("257"/\$.ccls. "428"/\$.ccls.) and "flip chip" same (transparent or clear) same (cover or cap or top) same chip	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 03:05
S64	123	("257"/\$.ccls. "428"/\$.ccls.) and "flip chip" same (transparent or clear) same (cover or cap or top) with chip	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 03:05
S65	72	("257"/\$.ccls. "428"/\$.ccls.) and "flip chip" same (transparent or clear) with (cover or cap or top) with chip	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 03:05

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S66	8	("257"/\$.ccls. "428"/\$.ccls.) and "flip chip" same (transparent or clear) with (cover or cap or top) with chip and (BGA or "ball grid")	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 03:08
S67	1	"5984190".pn.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 03:23
S68	364	(CSP or "flip chip" or "flip chip") and (transparent or clear) near3 (epoxy or resin or glob) same chip	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 03:24
S69	152	(CSP or "flip chip" or "flip chip") and (transparent or clear) near3 (epoxy or resin or glob) same chip and (ball or bga)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 03:24
S70	25	(CSP or "flip chip" or "flip chip") and (transparent or clear) near3 (epoxy or resin or glob) same chip and (ball or bga) and underfill	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 03:27
S71	56	(CSP or "flip chip" or "flip chip") and (transparent or clear) near3 (top or cover\$4 or encapsula\$4) same chip and (ball or bga) and underfill	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 03:34
S72	46	(CSP or "flip chip" or "flip-chip") and (transparent or clear) near3 (top or cover\$4 or encapsula\$4) same chip and (ball or bga) and underfill and (sens\$3 or optical\$3)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 11:51

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S73	64	(US-20040214409-\$ or	US-PGPUB;	OR	ON	2007/05/26 12:03
		US-20060102998-\$ or	USPAT;			
		US-20050282312-\$ or	JPO			
		US-20060154403-\$ or				
		US-20040084741-\$ or				
		US-20040159462-\$ or		!		
		US-20040104491-\$ or				
		US-20030062609-\$ or				
		US-20070020814-\$ or				
		US-20070013084-\$ or				
		US-20060237845-\$ or				
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		US-20070007001-\$ 01 US-20050133916-\$ or				
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		US-20070111388-\$ or				
		US-20060208349-\$ or				
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		US-20050189629-\$ or				
		US-20020105080-\$ or				
		US-20060076675-\$ or				
		US-20040257230-\$ or				
		US-20050224109-\$ or				
		US-20030064531-\$).did. or				
		(US-5925934-\$ or US-5866949-\$ or				
		US-7208335-\$ or US-7144800-\$ or				
		US-7129576-\$ or US-7042106-\$ or				
		US-5984190-\$ or US-5790728-\$ or				
		US-7122874-\$ or US-7015592-\$ or			i	ļ
		US-7002241-\$ or US-5197650-\$ or				
		US-4787143-\$ or US-5539976-\$ or				
Ì		US-6116493-\$ or US-5834340-\$ or				
		US-7135356-\$ or US-5566441-\$ or	Í			
		US-6476499-\$ or US-6288335-\$ or				
		US-5528825-\$ or US-6719205-\$ or				
		US-5887343-\$ or US-5644102-\$ or				
		US-6200828-\$ or US-6337122-\$).did.				
		or (US-4719502-\$).did. or				
		(JP-02222558-\$ or JP-61177748-\$ or				
		JP-59175751-\$ or JP-06196575-\$ or				
		JP-05267482-\$ or JP-03160748-\$ or				
		JP-58017640-\$ or JP-57147254-\$ or				
		JP-02148756-\$ or JP-61117853-\$ or				1
		JP-57071151-\$).did.				
		· ·		05	011	2007/05/26 12:00
S74	5	S73 and sensor with process\$4	US-PGPUB;	OR	ON	2007/05/26 12:09
			USPAT;			
			JPO			
S75	1	"6288905".pn.	US-PGPUB;	OR	ON	2007/05/26 12:13
3/3	1		USPAT;			
			JPO			

S76	90	"flip chip" same (die or chip) with (barcode or symbol\$4 or marking)	US-PGPUB; USPAT; JPO	OR	ON	2007/05/26 12:15
S77	0	"flip chip" same (die or chip) with (barcode)	US-PGPUB; USPAT; JPO	OR	ON	2007/05/26 12:15
S78	10	"flip chip" same (die or chip) with ("bar code")	US-PGPUB; USPAT; JPO	OR	ON	2007/05/26 12:16

S79	64	(US-20040214409-\$ or	US-PGPUB;	OR	ON	2007/05/26 12:18
		US-20060102998-\$ or	USPAT;		İ	
		US-20050282312-\$ or	JPO			
		US-20060154403-\$ or				
		US-20040084741-\$ or			İ	
		US-20040159462-\$ or			ł	
		US-20040104491-\$ or				
		US-20030062609-\$ or				
		US-20070020814-\$ or				
		US-20070013084-\$ or				
		US-20060237845-\$ or	:			
		US-20060237844-\$ or				
		US-20060226529-\$ or				
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		US-20070111388-\$ or				
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		US-20020105080-\$ or				
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		US-20030064531-\$).did. or				
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		US-7208335-\$ or US-7144800-\$ or				
		US-7129576-\$ or US-7042106-\$ or				
		US-5984190-\$ or US-5790728-\$ or				
		US-7122874-\$ or US-7015592-\$ or				
		US-7002241-\$ or US-5197650-\$ or				
		US-4787143-\$ or US-5539976-\$ or				
		US-6116493-\$ or US-5834340-\$ or				
		US-7135356-\$ or US-5566441-\$ or			1	
		US-6476499-\$ or US-6288335-\$ or				
		US-5528825-\$ or US-6719205-\$ or				
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		US-6200828-\$ or US-6337122-\$).did.				
		or (US-4719502-\$).did. or				
1		(JP-02222558-\$ or JP-61177748-\$ or				
İ		JP-59175751-\$ or JP-06196575-\$ or				
		JP-05267482-\$ or JP-03160748-\$ or				
1		JP-58017640-\$ or JP-57147254-\$ or				
		JP-02148756-\$ or JP-61117853-\$ or				
		JP-57071151-\$).did.				
S80	30	S79 and (barcode or "bar code")	US-PGPUB;	OR	ON	2007/05/26 12:29
			USPAT; JPO			
S81	259	"flip chip" and (sens\$4 or optical) and	US-PGPUB;	OR	ON	2007/05/26 12:30
		(barcode or "bar code") and package	USPAT;			
1		, , ,	JPO			

S82	72	"flip chip" and (sens\$4 or optical) and (barcode or "bar code") and package and ball	US-PGPUB; USPAT; JPO	OR	ON	2007/05/26 12:30
ļ		and ball	Jro			

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	118	("flip chip" or "flip-chip") same (transparent or clear) with (encapsulant or encapsulat\$4 or protect\$4)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/24 03:35
S2	56	("flip chip" or "flip-chip") same (transparent or clear) near3 (encapsulant or encapsulat\$4 or protect\$4)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/24 03:48
S3	0	"flip chip" same (protect\$4 or encapsulant or encapsulat\$4) with (clear or transparent) same (mark or marking or code or barcode or "bar code")	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/24 03:51
S4	118	"flip chip" same (protect\$4 or encapsulant or encapsulat\$4) with (clear or transparent)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/24 03:51
S5	40	"flip chip" same (protect\$4 or encapsulant or encapsulat\$4) with (clear or transparent) and (barcode or "bar code" or mark\$3 or symbol\$4 or indicia)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/24 04:01
S6	4	"flip chip" and ((encapsulant or encapsulat\$4 or protect\$4) with clear) and (ball or bump) and (underfill\$4) and (barcode or "bar code" or indicia or mark\$4 or symbol\$4)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/24 04:03
S7	12	"flip chip" and ((encapsulant or encapsulat\$4 or protect\$4 or resin) with clear) and (ball or bump) and (underfill\$4) and (barcode or "bar code" or indicia or mark\$4 or symbol\$4)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/24 04:03
S8	74	"flip chip" and ((encapsulant or encapsulat\$4 or protect\$4 or resin) with (transparent or clear)) and (ball or bump) and (underfill\$4) and (barcode or "bar code" or indicia or mark\$4 or symbol\$4)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/24 04:13
S9	46	("ball grid" or FPBGA or BGA or "flip chip" or "flip-chip") same (clear or transparent) near3 (encapsula\$4 or resin or cover\$3 or seal\$4 or protect\$4) and (underfill\$4)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/24 12:19
S10	33	("ball grid" or FPBGA or BGA or "flip chip" or "flip-chip") same ("bar code" or bacode)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/24 14:23

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S11	1	"6984866".pn.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/24 14:24
S12	9	("4760440" "5867368" "6040612" "6396116" "6413474" "6518656" "6566745" "6765236" "6787869"). PN. OR ("6984866").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/24 14:48
S13	0	beibi.in. and code	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/24 14:48
S14	5	beibi.in.	JPO	OR	ON	2007/05/24 14:48
S15	3941	package same (integrated or circuit or semiconductor) and (underfill\$4) and (encapsulat\$4 or glob or protect\$4 or resin) and (ball or bga or flip)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 01:31
S16	1596	package same (integrated or circuit or semiconductor) and (underfill\$4) same (encapsulat\$4 or glob or protect\$4 or resin) same (ball or bga or flip)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 01:32
S17	634	package same (integrated or circuit or semiconductor) same (underfill\$4) same (encapsulat\$4 or glob or protect\$4 or resin) same (ball or bga or flip)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 01:32
S18	15	package same (integrated or circuit or semiconductor) same (underfill\$4) same (encapsulat\$4 or glob or protect\$4 or resin) same (ball or bga or flip) same (barcode or mark\$4 or code or bar or symbol\$4)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 01:45
S19	1	"6639324" .pn.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 01:45
S20	377	"257"/\$.ccls. and package and (glob or transparent or clear) near3 (top or cover) and underfill	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 02:04
S21	341	"257"/\$.ccls. and package and (glob or transparent or clear) near3 (top or cover) and underfill and (ball)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 02:05
S22	41	"257"/\$.ccls. and package same (glob or transparent or clear) near3 (top or cover) same underfill and (ball)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 02:05
S23	44	"257"/\$.ccls. and package same (glob or transparent or clear) near3 (top or cover) same underfill\$3 and (ball)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 02:08

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S24	9	"257"/\$.ccls. and package same (transparent or clear) same (top or cover or protect\$4) same underfill\$3 same (ball) same (semiconductor or die or circuit)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 02:13
S25	11	"257"/\$.ccls. and package same (transparent or clear or glass) near4 (top or cover or protect\$4) same underfill\$3 same (semiconductor or die or circuit)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/05/26 02:14